



FCIconnect.com

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NOTES:

(1.) <u>MAT'L:</u>

HOUSING: LCP

**CONTACT:** COPPER ALLOY

<u>PLATING</u>

CONTACT: (SEE TABLE ON SHEET1) SOLDER BALL: (SEE TABLE ON SHEET1) EUTECTIC SnPb OR LEAD FREE 95.5Sn/4Aq/0.5Cu

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- 2. SOLDER BALLS WILL NOT BE PERFECT SPHERICAL SHAPE DUE TO REFLOW ATTACHMENT.
- 3. MATED HEIGHT EFFECTED BY CUSTOMER'S PCB PAD SIZE, PLATING, SOLDER REFLOW PROFILE, & SOLDER PASTE.
- 4. PLATING FOR -2XX SERIES DASH NOS. MEETS
  THE REQUIREMENTS OF NORTEL NPS25298-2
  (CENTRAL OFFICE ENVIRONMENT, 25 YEAR LIFE EXPECTANCY).
- (5) FOR PROPER APPLICATION FOLLOW FCI APPLICATION SPECIFICATION GS-20-033 LEAD FREE SOLDER BALLS WILL NOT SOLDER PROPERLY IN A LEADED SOLDER PROCESS DUE TO A HIGHER REFLOW TEMPERATURE. LEAD FREE PRODUCT IS THERFORE NOT BACKWARDS COMPATIBLE WITH LEADED OR SOME SOLDERING APPLICATIONS. REFERENCE FCI APPLICATION SPECIFICATION
- 6) THIS PRODUCT MEETS EUROPEAN UNION DIRECTIVES AND OTHER COUNTRY REGULATIONS AS DESCRIBED IN GS-22-008 PRODUCT MEETING THIS DIRECTIVE IS IDENTIFIED IN THE LOT CODE NUMBER MARKED ON EACH PART BY HAVING AN "X" IN THE SEVENTH CHARACTER POSITION

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mat'l	. code		surface / tolerance					proje	ction		product family										
	SEE 1	NOTE	1	ASME Y14.5 ✓ ASME Y14.5						⊕-母			MEG-ARRAY								
ltr	ecn no	dr	date	tolerances unless otherwise specified									title								
N				angle	۳ ا	.XX±.3 .XXX±.13 .XXX±.051			±.3		ММ		0mm PLUG ASSY.								
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				0° ±	2.					scale	2	:1	1	8 X 30= 240 PO						si.	
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				engr	T	T LEMKE		11.1	4.97								~ 4 -7				,
				chr	T LEMKE		ΚE	11.14.97				74213  A4							<del> </del> 44		
				appd	Т	LEMP	ΚE	11.1	4.97	_			type CUSTOMER Drawing								
shee	t revi	sion																			
index	she she	et																			

form: A4mmXLc

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PDM: Rev:N